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AKAMATSU TOSHIMASA**(54) **RESIN SEALING STRUCTURE OF
SEMICONDUCTOR DEVICE**

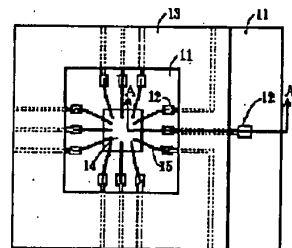
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(57) Abstract:

PROBLEM TO BE SOLVED: To stop flow of coating resin to an outer periphery at a desired position and prevent resin from covering an adjacent part due to flow by forming resist protecting the top of a wiring board in an outer periphery of a semiconductor device of a material which repels resin.

SOLUTION: Spot coat resin 16 which is viscous liquid is dropped on a semiconductor stop 14 from syringe, spreads while flowing on a wiring board, is repelled by surface tension of solder resist 13 with property to repel the spot coat resin 16 on reaching a frame of the solder resist 13 and is prevented from flowing onto solder resist. Then, the spot coat resin 16 is subjected to hardening reaction treatment of resin and resin sealing treatment is finished. The structure has an effect to prevent resin from flowing without enlarging a space especially. Failure regarding resin coating is prevented by stopping flow of resin by carrying out resin hardening treatment while holding a range of resin coating in a proper form.

(a)



(b)

